ICS 31.180 SLOVENSKÁ TECHNICKÁ NORMA Apríl 2017

STN	**Skúšobné metódy na elektrotechnické materiály, dosky s plošnými spojmi a iné spájacie štruktúry a zostavy. Časť 2-719: Skúšobné metódy na materiály na spájacie štruktúry. Relatívna permitivita a stratový činiteľ (500 MHz až 10 GHz).**	**STN EN 61189-2-719** 34 6513

Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 2-719: Test methods for materials for interconnection structures - Relative permittivity and loss tangent (500 MHz to 10 GHz)

Táto norma obsahuje anglickú verziu európskej normy.
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 03/17

Obsahuje: EN 61189-2-719:2016, IEC 61189-2-719:2016

124504

EUROPEAN STANDARD

NORME EUROPÉENNE

EUROPÄISCHE NORM

EN 61189-2-719

October 2016

ICS 31.180

English Version

Test methods for electrical materials, printed boards and other interconnection structures and assemblies - Part 2-719: Test methods for materials for interconnection structures - Relative permittivity and loss tangent (500 MHz to 10 GHz) (IEC 61189-2-719:2016)

Méthode d'essai pour les matériaux électriques, les cartes imprimées et autres structures d'interconnexion et ensembles - Partie 2-719: Méthodes d'essai des matériaux pour structures d'interconnexion - Permittivité relative et tangente de perte (500 MHz à 10 GHz) (IEC 61189-2-719:2016)

Prüfverfahren für Elektromaterialien, Leiterplatten und andere Verbindungsstrukturen und Baugruppen - Teil 2-719: Prüfverfahren für Materialien von Verbindungsstrukturen - Relative Permittivität und Verlustfaktor (500 MHz bis 10 GHz) (IEC 61189-2-719:2016)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels

Ref. No. EN 61189-2-719:2016 E

EN 61189-2-719:2016

European foreword

The text of document 91/1366/FDIS, future edition 1 of IEC 61189-2-719, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 61189-2-719:2016.

The following dates are fixed:

• latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement	(dop)	2017-05-16
• latest date by which the national standards conflicting with the document have to be withdrawn	(dow)	2019-08-16

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Annex ZA
(normative)

Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu

Publication	Year	Title	EN/HD	Year
IEC 60194	-	Printed board design, manufacture and assembly - Terms and definitions	-	-

IEC 61189-2-719

Edition 1.0 2016-07

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FOREWORD

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International Standard IEC 61189-2-719 has been prepared by IEC technical committee 91: Electronics assembly technology.

The text of this standard is based on the following documents:

FDIS	Report on voting
91/1366/FDIS	91/1380/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 61189 series, published under the general title *Test methods for electrical materials, printed boards and other interconnection structures and assemblies*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

IMPORTANT – The 'colour inside' logo on the cover page of this publication indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this document using a colour printer.

TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARDS AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –

Part 2-719: Test methods for materials for interconnection structures – Relative permittivity and loss tangent (500 MHz to 10 GHz)

1 Scope

This part of IEC 61189 specifies a test method of relative permittivity and loss tangent of printed board and assembly materials, expected to be determined 2 to 10 of relative permittivity and 0,001 to 0,050 of loss tangent at 500 MHz to 10 GHz.

2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60194, *Printed board design, manufacture and assembly – Terms and definitions*